



Device Material Content

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Assembly: ASEM
Size (mm): 27 x 27

Package Code:

BG756

Lead pitch (mm): 0.8

Package: 756 caBGA
Total Device Weight 2.483 Grams

Products:

MSL: 3

July, 2019

FE5

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.07%	0.0266	1.07%	0.0266	Silicon chip	7440-21-3	100.00%	Die size: 6.55 x 7.04 mm
Mold Compound	44.79%	1.1122	3.14%	0.0779	Epoxy Resin	-	7.00%	Mold Compound: Sumitomo G750SE (ULA)
			2.24%	0.0556	Phenol Novolac	9003-35-4	5.00%	
			2.24%	0.0556	Metal Hydroxide	-	5.00%	
			0.22%	0.0056	Carbon Black	1333-86-4	0.50%	
			36.95%	0.9176	Silica Fused	60676-86-0	82.50%	
D/A Epoxy	0.16%	0.0040	0.13%	0.00318	Silver	7440-22-4	80.00%	Die attach epoxy: Henkel (Ablebond) 2100A
			0.03%	0.00079	Esters & resins	-	20.00%	
Wire	0.20%	0.0050	0.20%	0.0049	Copper	7440-50-8	98.50%	0.8 mil diameter; 1 wire per solder ball
			0.00%	0.0001	Palladium	7440-05-3	1.50%	
Solder Balls	7.59%	0.1885	7.32%	0.1819	Tin (Sn)	7440-31-5	96.50%	SAC305
			0.23%	0.0057	Silver (Ag)	7440-22-4	3.00%	
			0.04%	0.0009	Copper (Cu)	7440-50-8	0.50%	
Substrate	30.02%	0.7455	0.00%	0.0000	BT Resins	-	32.00%	BT Resin CCL-HL832NX-A*
			0.00%	0.0000	Glass fiber	65997-17-3	68.00%	
Foil	11.22%	0.2786	0.00%	0.0000	Copper	7440-50-8	84.56%	
			0.00%	0.0000	Nickel plating	7440-02-0	14.70%	
			0.00%	0.0000	Gold plating	7440-57-5	0.74%	
Solder Mask	4.95%	0.1228	0.00%	0.0000	Quartz	14808-60-7	54.37%	Solder mask PSR4000 AUS 308
			0.00%	0.0000	Dipropylene glycol monomethyl ether	34590-94-8	7.33%	
			0.00%	0.0000	Morpholine derivative	71868-10-5	3.32%	
			0.00%	0.0000	Silicon dioxide	7631-86-9	3.00%	
			0.00%	0.0000	Silica, amorphous	112945-52-5	3.00%	
			0.00%	0.0000	Carbon black	1333-86-4	0.24%	
			0.00%	0.0000	Trade secret ingredients	-	28.74%	

Notes: * 0.30% max. concentration (of total pkg wt.) of Bisphenol A (CAS# 80-05-7), contained in substrate laminate material as impurity - not intentionally added.

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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Rev. D